

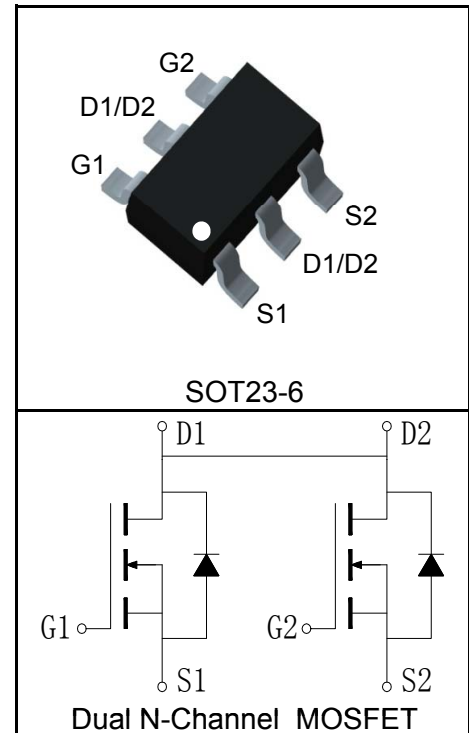
### Features

- 20V/6A,  
 $R_{DS(ON)} = 18m\Omega(Typ.)@V_{GS}=4.5V$   
 $R_{DS(ON)} = 23m\Omega(Typ.)@V_{GS}=2.5V$
- Low  $R_{DS(ON)}$
- Super High Dense Cell Design
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

### Applications

- Power Management

### Pin Description



### Absolute Maximum Ratings

| Symbol                                                        | Parameter                                       |                      | Rating     | Unit |
|---------------------------------------------------------------|-------------------------------------------------|----------------------|------------|------|
| Common Ratings (T <sub>A</sub> = 25°C Unless Otherwise Noted) |                                                 |                      |            |      |
| V <sub>DSS</sub>                                              | Drain-Source Voltage                            |                      | 20         | V    |
| V <sub>GSS</sub>                                              | Gate-Source Voltage                             |                      | ±12        |      |
| T <sub>J</sub>                                                | Maximum Junction Temperature                    |                      | 150        | °C   |
| T <sub>STG</sub>                                              | Storage Temperature Range                       |                      | -55 to 150 | °C   |
| I <sub>S</sub>                                                | Diode Continuous Forward Current                | T <sub>A</sub> =25°C | 1.7        | A    |
| Mounted on Large Heat Sink                                    |                                                 |                      |            |      |
| I <sub>DP</sub> <sup>①</sup>                                  | 300μs Pulse Drain Current Tested                | T <sub>A</sub> =25°C | 24         | A    |
| I <sub>D</sub> <sup>②</sup>                                   | Continuous Drain Current(V <sub>GS</sub> =4.5V) | T <sub>A</sub> =25°C | 6          | A    |
|                                                               |                                                 | T <sub>A</sub> =70°C | 4.5        |      |
| P <sub>D</sub>                                                | Maximum Power Dissipation                       | T <sub>A</sub> =25°C | 1.25       | W    |
|                                                               |                                                 | T <sub>A</sub> =70°C | 0.75       |      |
| R <sub>θJC</sub>                                              | Thermal Resistance-Junction to Case             |                      | -          | °C/W |
| R <sub>θJA</sub> <sup>③</sup>                                 | Thermal Resistance-Junction to Ambient          |                      | 100        | °C/W |
| Drain-Source Avalanche Ratings                                |                                                 |                      |            |      |
| E <sub>AS</sub> <sup>④</sup>                                  | Avalanche Energy, Single Pulsed                 |                      | TBD        | mJ   |

**Electrical Characteristics** ( $T_A=25^{\circ}\text{C}$  Unless Otherwise Noted)

| Symbol                                   | Parameter                        | Test Condition                                                                        | RU8205C6 |      |      | Unit |
|------------------------------------------|----------------------------------|---------------------------------------------------------------------------------------|----------|------|------|------|
|                                          |                                  |                                                                                       | Min.     | Typ. | Max. |      |
| Static Characteristics                   |                                  |                                                                                       |          |      |      |      |
| BV <sub>DSS</sub>                        | Drain-Source Breakdown Voltage   | V <sub>GS</sub> =0V, I <sub>DS</sub> =250μA                                           | 20       |      |      | V    |
| I <sub>DSS</sub>                         | Zero Gate Voltage Drain Current  | V <sub>DS</sub> =20V, V <sub>GS</sub> =0V                                             |          |      | 1    | μA   |
|                                          |                                  | T <sub>J</sub> =125°C                                                                 |          |      | 30   |      |
| V <sub>GS(th)</sub>                      | Gate Threshold Voltage           | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250μA                             | 0.5      | 0.7  | 1.5  | V    |
| I <sub>GSS</sub>                         | Gate Leakage Current             | V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V                                            |          |      | ±100 | nA   |
| R <sub>DS(ON)</sub> <sup>⑤</sup>         | Drain-Source On-state Resistance | V <sub>GS</sub> =4.5V, I <sub>DS</sub> =6A                                            |          | 18   | 22   | mΩ   |
|                                          |                                  | V <sub>GS</sub> =2.5V, I <sub>DS</sub> =5A                                            |          | 23   | 28   | mΩ   |
| Diode Characteristics                    |                                  |                                                                                       |          |      |      |      |
| V <sub>SD</sub> <sup>⑤</sup>             | Diode Forward Voltage            | I <sub>SD</sub> =1A, V <sub>GS</sub> =0V                                              |          |      | 1    | V    |
| t <sub>rr</sub>                          | Reverse Recovery Time            | I <sub>SD</sub> =1A, dI <sub>SD</sub> /dt=100A/μs                                     |          | 15   |      | ns   |
| Q <sub>rr</sub>                          | Reverse Recovery Charge          |                                                                                       |          | 8    |      | nC   |
| Dynamic Characteristics <sup>⑥</sup>     |                                  |                                                                                       |          |      |      |      |
| R <sub>G</sub>                           | Gate Resistance                  | V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz                                      |          | 1.5  |      | Ω    |
| C <sub>iss</sub>                         | Input Capacitance                | V <sub>GS</sub> =0V, V <sub>DS</sub> =10V, Frequency=1.0MHz                           |          | 590  |      | pF   |
| C <sub>oss</sub>                         | Output Capacitance               |                                                                                       |          | 125  |      |      |
| C <sub>rss</sub>                         | Reverse Transfer Capacitance     |                                                                                       |          | 90   |      |      |
| t <sub>d(ON)</sub>                       | Turn-on Delay Time               | V <sub>DD</sub> =10V, I <sub>DS</sub> =6A, V <sub>GEN</sub> =4.5V, R <sub>G</sub> =6Ω |          | 8    |      | ns   |
| t <sub>r</sub>                           | Turn-on Rise Time                |                                                                                       |          | 15   |      |      |
| t <sub>d(OFF)</sub>                      | Turn-off Delay Time              |                                                                                       |          | 33   |      |      |
| t <sub>f</sub>                           | Turn-off Fall Time               |                                                                                       |          | 13   |      |      |
| Gate Charge Characteristics <sup>⑥</sup> |                                  |                                                                                       |          |      |      |      |
| Q <sub>g</sub>                           | Total Gate Charge                | V <sub>DS</sub> =16V, V <sub>GS</sub> =4.5V, I <sub>DS</sub> =6A                      |          | 10   |      | nC   |
| Q <sub>gs</sub>                          | Gate-Source Charge               |                                                                                       |          | 1.6  |      |      |
| Q <sub>gd</sub>                          | Gate-Drain Charge                |                                                                                       |          | 3.4  |      |      |

- Notes:
- ① Pulse width limited by safe operating area.
  - ② Calculated continuous current based on maximum allowable junction temperature.
  - ③ When mounted on 1 inch square copper board,  $t \leq 10\text{sec}$ . The value in any given application depends on the user's specific board design.
  - ④ Limited by  $T_{Jmax}$ . Starting  $T_J = 25^{\circ}\text{C}$ .
  - ⑤ Pulse test; Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
  - ⑥ Guaranteed by design, not subject to production testing.

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**Ordering and Marking Information**

| Device   | Marking <sup>①</sup> | Package | Packaging | Quantity | Reel Size | Tape width |
|----------|----------------------|---------|-----------|----------|-----------|------------|
| RU8205C6 | 4XYWW                | SOT23-6 | Tape&Reel | 3000     | 7"        | 8mm        |

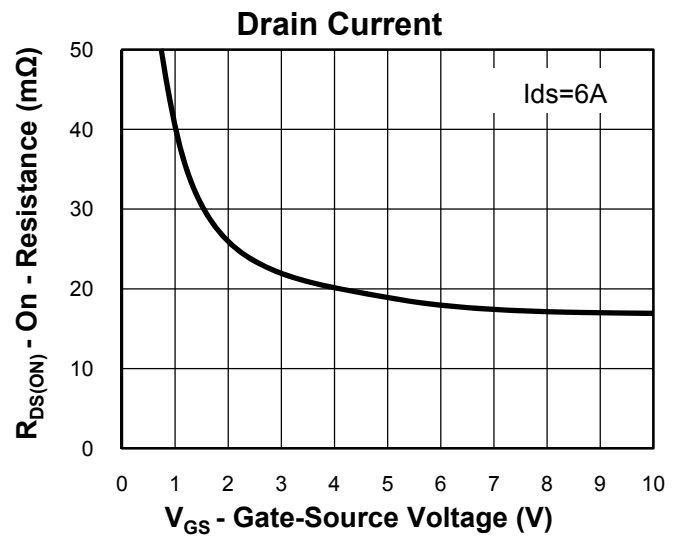
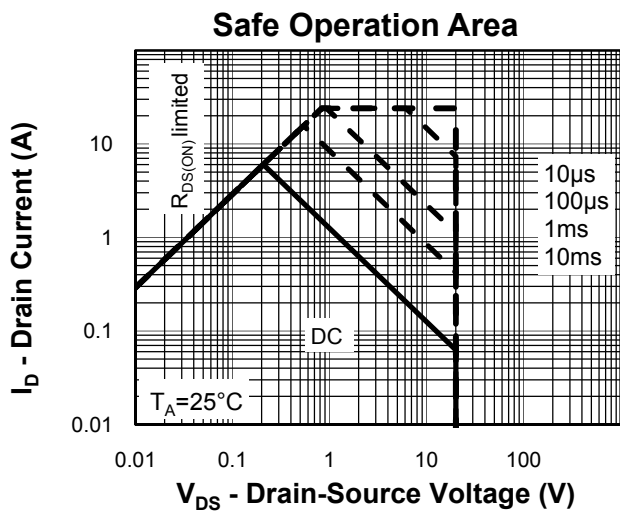
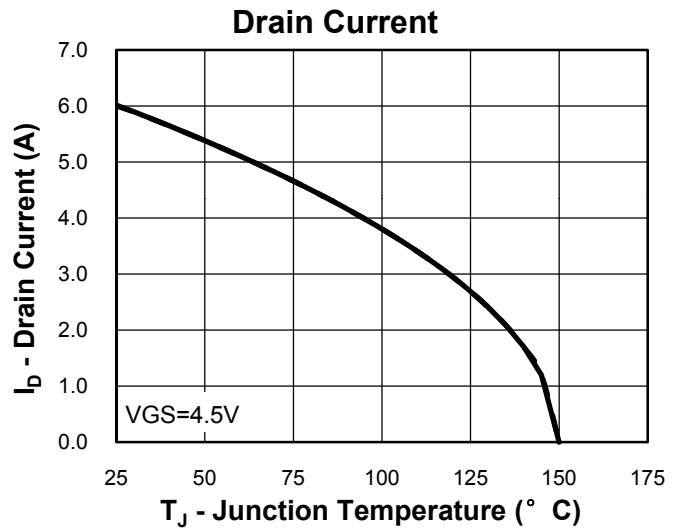
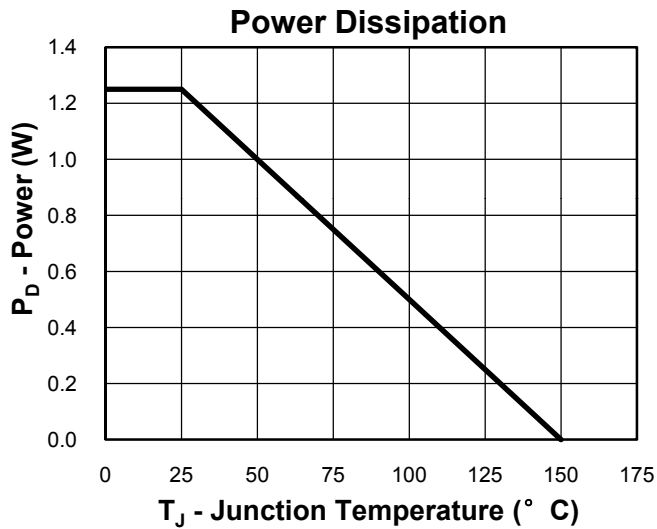
① The following characters could be different and means:

X =Assembly site code

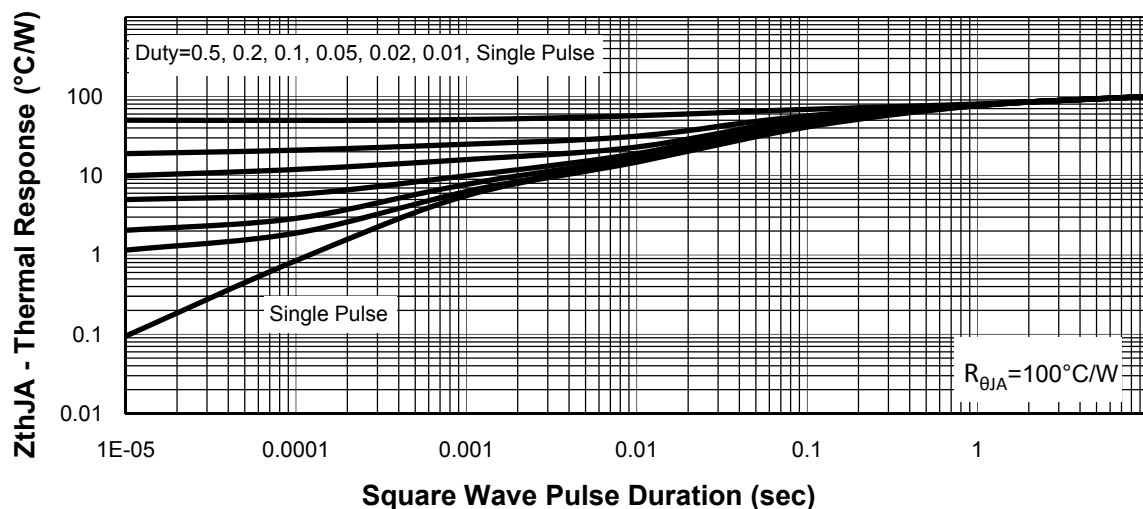
Y =Year

WW =Work Week

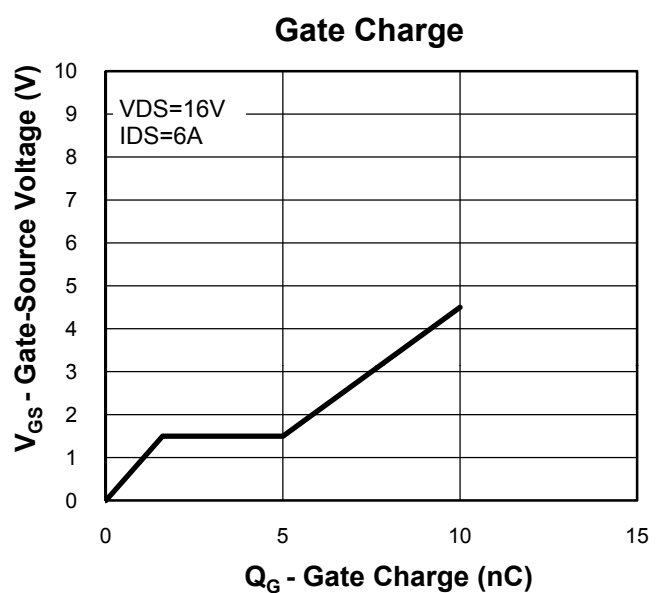
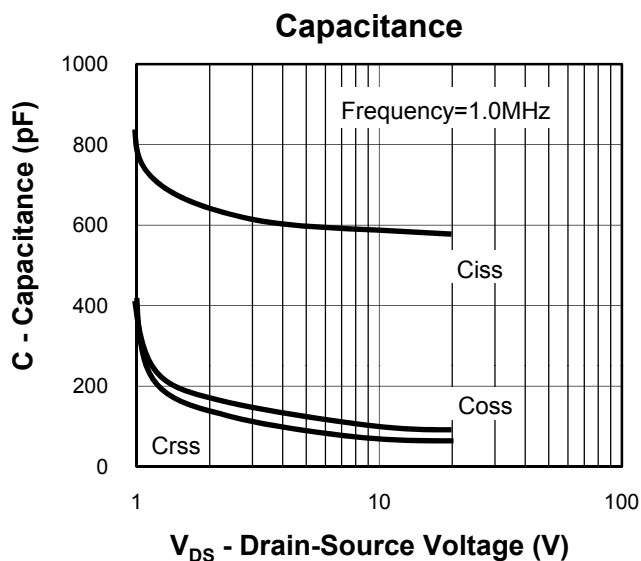
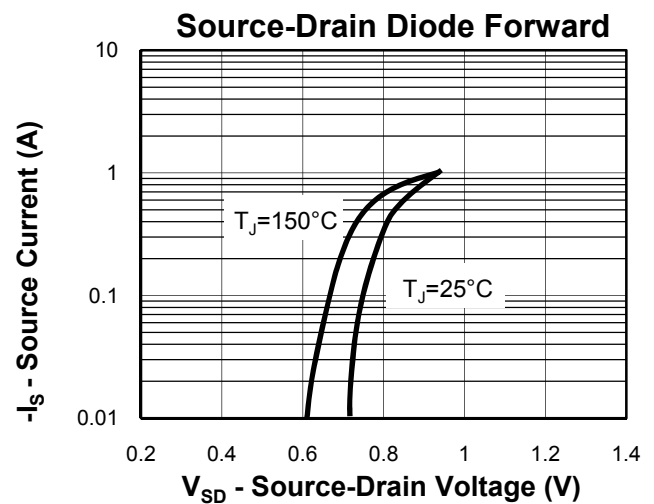
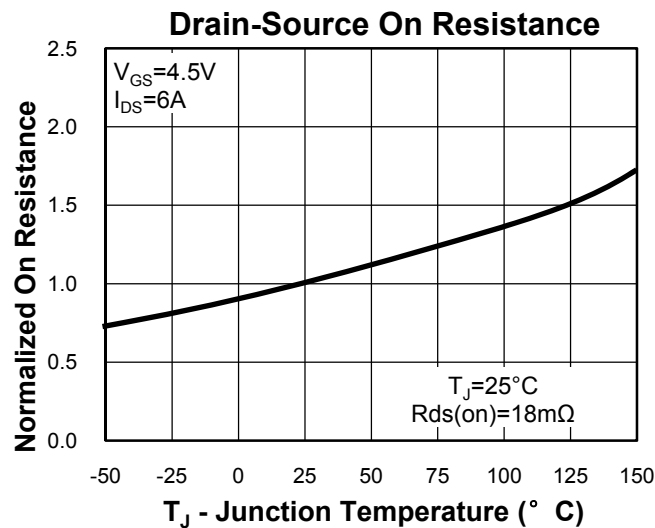
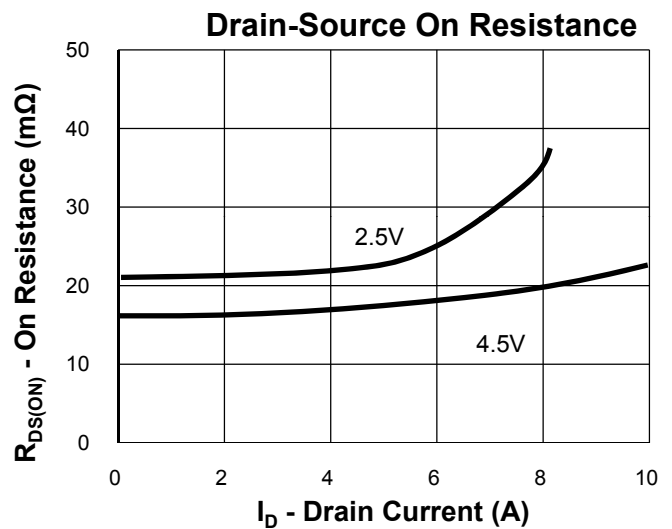
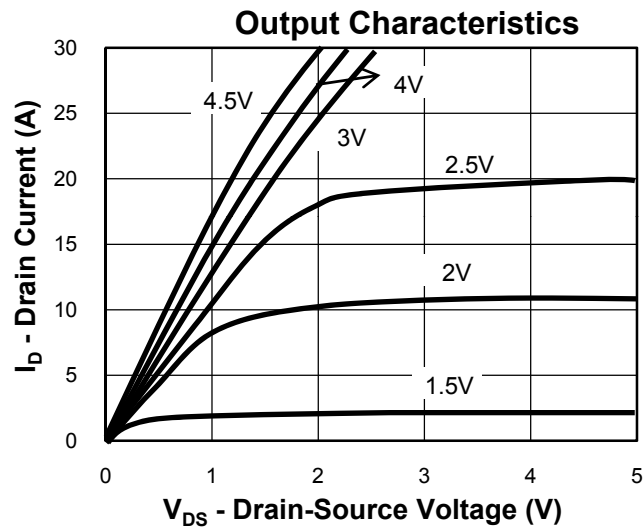
## Typical Characteristics



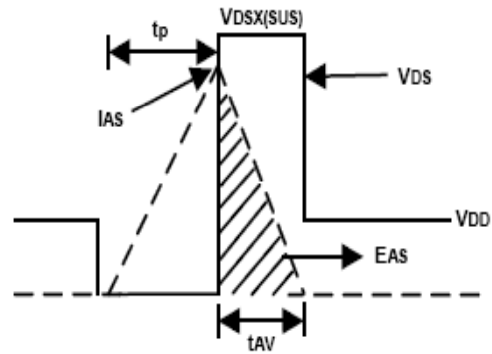
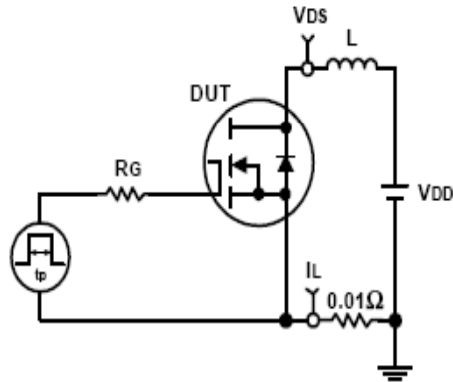
## Thermal Transient Impedance



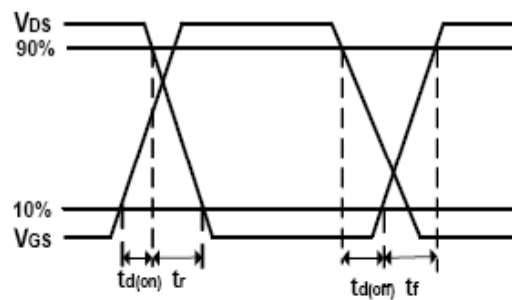
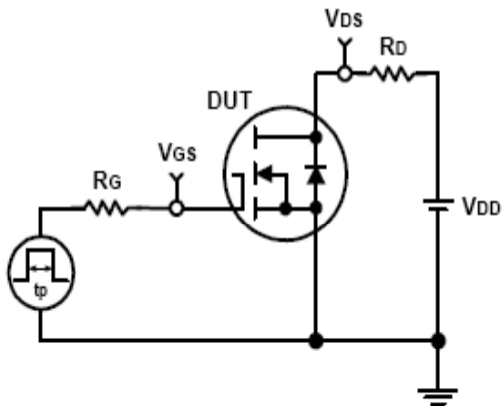
## Typical Characteristics



## Avalanche Test Circuit and Waveforms

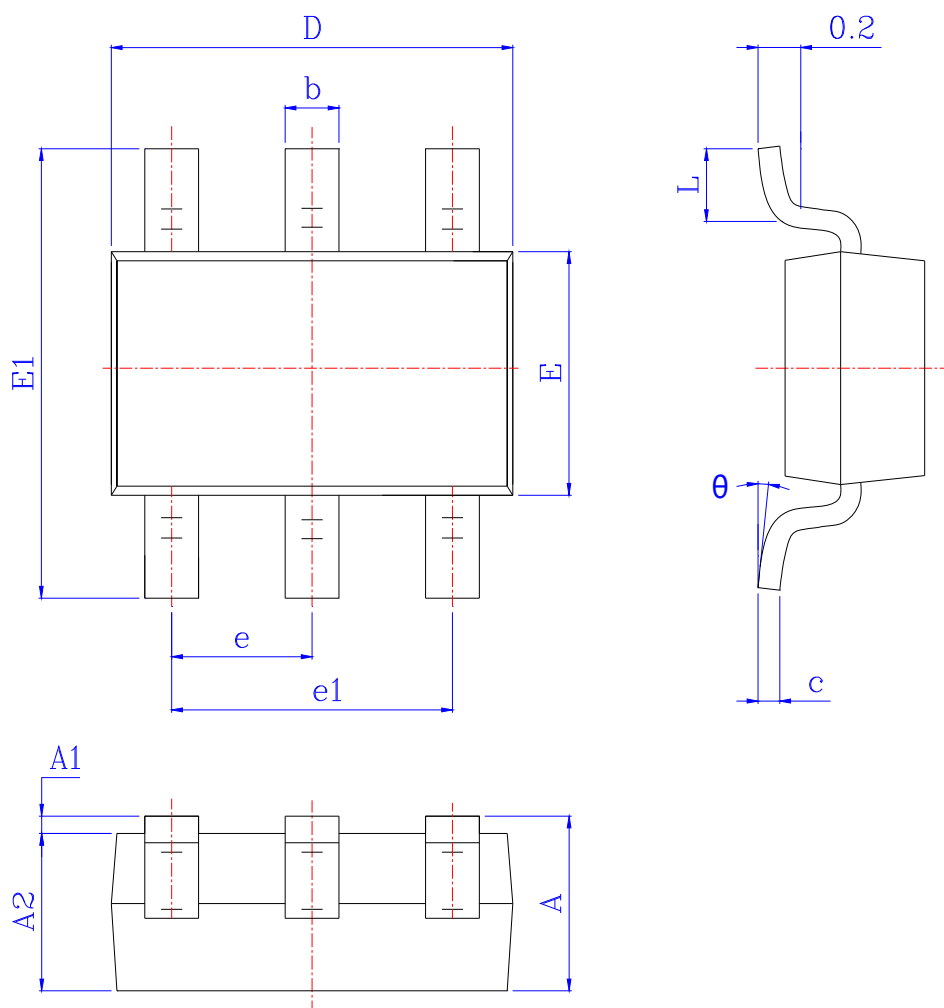


## Switching Time Test Circuit and Waveforms



**Package Information**

**SOT23-6**



| SYMBOL | MM       |       |       | INCH     |       |       |
|--------|----------|-------|-------|----------|-------|-------|
|        | MIN      | NOM   | MAX   | MIN      | NOM   | MAX   |
| A      | 0.950    | 1.150 | 1.450 | 0.037    | 0.045 | 0.057 |
| A1     | 0.000    | 0.060 | 0.150 | 0.000    | 0.002 | 0.006 |
| A2     | 0.900    | 1.100 | 1.300 | 0.035    | 0.043 | 0.051 |
| b      | 0.300    | 0.400 | 0.500 | 0.012    | 0.016 | 0.020 |
| c      | 0.080    | 0.140 | 0.200 | 0.003    | 0.006 | 0.008 |
| D      | 2.800    | 2.900 | 3.050 | 0.110    | 0.114 | 0.120 |
| E      | 1.500    | 1.600 | 1.750 | 0.059    | 0.063 | 0.069 |
| E1     | 2.600    | 2.800 | 3.000 | 0.102    | 0.110 | 0.118 |
| e      | 0.950BSC |       |       | 0.037BSC |       |       |
| e1     | 1.800    | 1.900 | 2.000 | 0.071    | 0.075 | 0.079 |
| L      | 0.300    | 0.450 | 0.600 | 0.012    | 0.018 | 0.024 |
| θ      | 0°       | 4°    | 8°    | 0°       | 4°    | 8°    |

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